

## **Quarterly Reliability Monitoring Results**

## Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number PESD5V0S1BL-Q Part Description												
										Nexperia DHAM	Protection			
								Assembly reliability labs		MCD package				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects								
	TEST													
	Pre- and Post-Stress													
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below								
		JESD22-A113												
		Bake Tamb = 125 °C	24 hours											
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours			_								
# A1	Preconditioning	Reflow soldering	3 cycles	211	12520	0								
		MIL-STD-750-1												
	HTRB	M1038 Method A												
# B1	Bias	Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hauma	166	10040	0								
# DI	Dias	reverse voltage	1000 hours	166	10040	U								
	тс	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	78	4640	0								
# A4			1000 Cycles	70	4040	0								
	UHAST	JESD22-A118												
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %		57	3420	0								
		JESD22-A102	— 96 hours											
	AC	Tamb = 121 °C, RH = 100 %												
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)												
	H3TRB	JESD22-A101												
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of												
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	75	4460	0								
		MIL-STD-750 Method 1037												
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =												
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.								
	RSH	JESD22-A111												
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.								
	SD													
# C10	Solderability	J-STD-002		111	1110	0								

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	10040	0	0,42	2,36E+09

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